

## TI 参考设计: TIDA-00847

# 采用具有集成电源的数字隔离器的尺寸和成本优化型二进制输入模块参考设计



### 说明

TIDA-00847 设计展示了一个四通道直流输入二进制输入模块 (BIM) 的尺寸和成本优化型架构, 该模块在测量精度和状态指示方面进行了改进, 仅使用两款 TI 产品即可简化系统设计。基于 MCU 的 BIM 可提高测量分辨率, 因此改善了系统性能, 包括提供可重复的准确故障指示, 并且无需多个硬件版本 (将同一设计用于多个标称电压输入), 从而减少设计、测试、制造和现场支持的工作量。在此 TI 参考设计中, 四个输入通道配置为组隔离输入, 因此可将每个通道的成本降至最低。一个 10 位 ADC 可测量大范围的直流输入, 且精度达到  $\pm 3\% \pm 1V$ 。此设计已执行针对 EMI 和 EMC 的预合规性测试。

### 资源

<a href="#">TIDA-00847</a>	设计文件夹
<a href="#">ISOW7841</a>	产品文件夹
<a href="#">ISO7741</a>	产品文件夹
<a href="#">MSP430G2332</a>	产品文件夹
<a href="#">MSP430FR2111</a>	产品文件夹
<a href="#">LMV614</a>	产品文件夹
<a href="#">SN6505b</a>	产品文件夹
<a href="#">TPS3808</a>	产品文件夹
<a href="#">TPS22944</a>	产品文件夹
<a href="#">TPS60241</a>	产品文件夹
<a href="#">SN6501</a> 中删除了 <a href="#">LMV551</a> 中添加了 <a href="#">SN6501</a>	产品文件夹
<a href="#">TPS70933</a>	产品文件夹



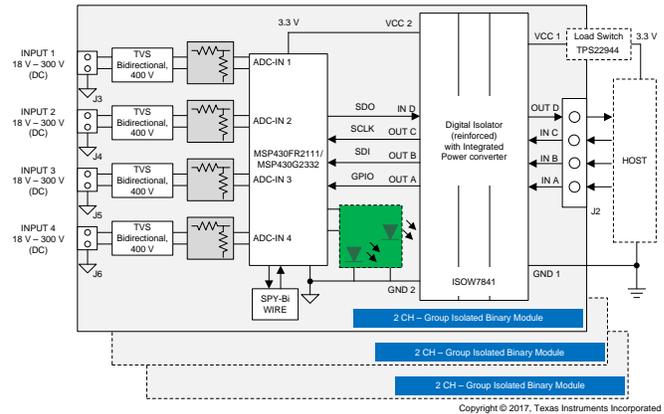
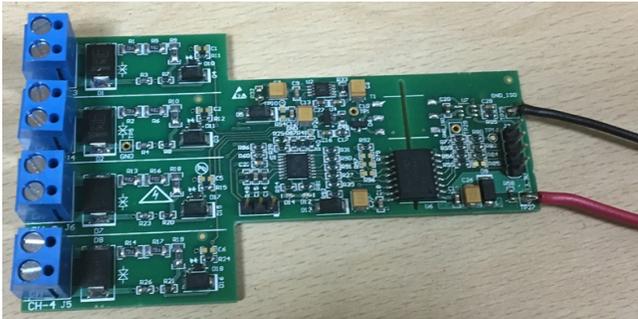
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### 特性

- 基于增强型隔离 ISOW7841 或 ISOW7841F 的 BIM 设计; 具有集成高效率的数字隔离器; 具有软启动功能的功率转换器以及 75mA 电流输出 (四路, 具有适用于 GPIO、SPI 或 UART 接口的各种配置), 可简化系统设计
- ISOW7841 直流输出针对 70mA 负载 (pkpk) 提供 46% 的效率以及 100mV 的输出纹波
- 基于 MSP430G2332 或 MSP430FR2111 MCU 的四通道直流输入或双通道交流/直流电压测量类型 BIM
- 基于 LMV614 运算放大器的信号调节, 增益为 1 倍和 3.4 倍, 可增大测量范围, 直流电平的稳定基准使用 LM4041 和 LMV551 来平移输入
- 两个 LED 提供二进制输入的状态指示
- 在整个输入范围内精度不超过测量值  $\pm 1V$  的  $\pm 3\%$
- 通过了基于 IEC61000-4 和 CISPR 22 标准的 EMI 和 EMC 预合规性测试
- 对于 BIM 输入, 阻抗大于 300k $\Omega$ , 在输入为 276V 时电流消耗小于 1mA

### 应用

- 多功能保护继电器
- 间隔控制器
- 合并单元
- 终端单元: RTU、FTU、DTU
- 适用于工厂自动化的 PLC



该 TI 参考设计末尾的重要声明表述了授权使用、知识产权问题和其他重要的免责声明和信息。

## 1 System Description

The binary inputs to the protection relay or other grid infrastructure end equipment are called under the following names:

- Binary input
- Digital input
- Control input
- Status indication input

These names are based on the functions they perform. These inputs are referred as binary inputs in this design guide. Binary inputs have wide applications. The binary input module specifications differ with OEMs. The binary inputs are designed as modules and based on application one or more modules are used. Below is the summary of some of the Applications, functionalities, and specifications. These inputs have galvanic isolation from internal circuits, generally optocoupler are used for isolation. Number of binary inputs per module can vary as 4, 8, 16, or 32. The binary inputs are organized in groups (depending upon application) with a common wire. In some of the applications the inputs are channel isolated.

Key specifications include nominal voltages of 24-V DC, 48 to 60-V DC, 110 to 125-V DC/AC, and 220-V DC/AC,  $\pm 20\%$  or multi-voltage (24 to 250-V DC/AC), and power consumption per input of 2 to 6 mA with a maximum power dissipation of 0.45 W  $\pm 20\%$  per input or a short peak current ( $> 25$  mA).

## 1.1 **BIM Application and Specifications**

### 1.1.1 **BIM Applications**

Binary inputs are used in grid applications for substation battery monitoring, bay or substation interlocking, breaker status indication, general interrogations, LED tests, diagnostics (self-test), fault indication (alarm), and configuration changes (operated with new settings to perform different functionality).

#### 1.1.1.1 **Multifunction Protection Relay**

Protection relays are connected across the primary equipment generating, transmitting, and distributing power to protect the equipment against faults that may damage the equipment. Protection relay inputs include AC voltage and current, DC transducer input, and binary inputs. The binary inputs indicating the status of the equipment being monitored for implementing the protection algorithm.

#### 1.1.1.2 **Bay Controller**

The bay control unit provides fully automated control of substation switching devices. After the switching device is configured and the required interlocking is provided, the bay controller performs the required function independently. The status, alarm, diagnostics, and the interlocking inputs to the bay controller are provided by the BIM.

#### 1.1.1.3 **Merging Unit**

The merging unit acquires AC currents or voltages from conventional current and voltage transformers (CTs and PTs). It converts these analog signals into digital values and transmits them using IEC 61850 standard using Ethernet connections. Along with the analog values, the status inputs provided by the primary equipment can be monitored and communicated. The status inputs to the merging unit are the binary inputs varying between 18- to 300-V DC.

#### 1.1.1.4 **Terminal Unit—RTU, FTU, DTU**

In the electrical power industry, equipment such as RTU, DTU, and FTU are switch monitoring devices installed in the substation close to the feed breakers (a disconnecter that is located in series at the end of a feeder, within a substation bay, in order to isolate the feeder from the system). These can be used for automated functions such as monitoring, protection, and communication in a ring network cabinet in the distribution substation and master station with the implementation of monitoring and fault identification, isolation, and power recovery of the fault in the distribution network. The monitored inputs can be AC analog input or DC transducer input of binary input. The binary inputs provide status or interlocking inputs.

## 1.1.2 TI Design Specifications for AC/DC BIM

表 1 提供宽输入两通道 AC 或 DC 输入 BIM TI 设计规格。

表 1. AC/DC BIM—Electrical Specifications

SERIAL NUMBER	PARAMETERS	DESCRIPTION	COMMENTS
1	Number of inputs	2 with provision for status indication using LED	Inputs share common ground
2	Input voltage range	20- to 270-V AC, 15- to 300-V DC	Maximum voltage $\leq$ 300-V AC/DC
3	Signal frequency	DC or AC (50 or 60 Hz)	—
4	Measurement resolution	<1-V steps for values between 20- to 270-V AC, 15- to 300-V DC	—
5	Gain amplifier	Two gains: $\times 1$ , $\times 3.4$	—
6	Measurement accuracy	$\pm 3\%$ of measured value $\pm 1$ V	Communicates through SPI to the host
7	Input impedance	$\geq 300$ k $\Omega$	—
8	Solution approach	Low-cost, small pin count MCU, digital isolator with integrated power, gain amplifier	—
9	ADC	Internal 10-bit ADC using MSP430G2332	—
10	LED indication	Two LEDs provided for binary status indication	—
11	Binary input current or power consumption	< 1 mA at 300-V DC	Does not include wetting current
12	Response time	$\geq 10$ ms	Measurement averaged
13	Input wetting resistance	$\geq 2.5$ k $\Omega$	PWM controlled
14	Isolator type	Digital isolator ISOW7841 or ISOW7841F with integrated power up to a 75-mA current output	Efficiency $\geq 46\%$
15	Isolation approach	Group isolated	Reinforced isolation
16	EMC tests	IEC 61000-4-2 ESD, IEC 61000-4-4 EFT, IEC 61000-4-5 Surge, IEC 61000-4-6 Immunity to radio frequency induced signals, IEC 61000-4-12 Ring wave immunity, IEC 61000-4-18 Damped oscillatory waves immunity	See 4.3 节
17	EMI tests	Emission tests as per EN 55022, class A, Conducted Emission, Radiated Emission	See 4.3 节

### 1.1.3 TI Design Specifications DC BIM

表 2 提供宽输入四通道 DC 输入 BIM TI 设计规格:

**表 2. Four-Channel DC BIM Electrical Specifications**

SERIAL NUMBER	PARAMETERS	DESCRIPTION	COMMENTS
1	Number of inputs	4 with provision for status indication	Inputs share common ground
2	Operating voltage ranges: DC	18- to 264-V DC: Measurement	Maximum input $\leq$ 300-V DC
3	Measurement resolution	$< 1$ -V steps for nominal values (24 to 240 V)	—
4	Measurement accuracy	$\pm 3.0\%$ of measured value $\pm$ step size	SPI or UART interface to the Host
5	Input impedance	$\geq 300$ k $\Omega$	—
6	Solution approach	Low-cost, small pin count MCU, digital isolator with integrated power	—
7	ADC	Internal 10-bit ADC using MSP430G2332 or MSP430FR2111	—
8	LED indication	Two LEDs provided for binary status indication	—
9	Binary input current or power consumption	$< 1$ mA at 300-V DC	—
10	Minimum response time	$\geq 3$ ms	Measurement averaged
11	Isolator type	Digital isolator ISOW7841 or ISOW7841F with integrated power up to a 75-mA current output or digital isolator with external transformer-based isolated power	Efficiency $\geq 46\%$
12	Isolation approach	Group isolated	Reinforced isolation
13	EMC tests	IEC 61000-4-2 ESD, IEC 61000-4-4 EFT, IEC 61000-4-5 Surge, IEC 61000-4-6 immunity to radio frequency induced signals, IEC 61000-4-12 Ring wave immunity, IEC 61000-4-18 Damped oscillatory waves immunity	See 4.3 节
14	EMI tests	Emission tests as per EN 55022, class A, Conducted Emission, Radiated Emission	See 4.3 节

## 2 System Overview

This TIDA-00847 design showcases space and cost-optimized architecture for a four-channel DC input binary module or two-channel AC or DC input binary module with improved measurement accuracy and status indication using different design approaches, simplifying the overall system design. An MCU-based binary module improves measurement resolution of the binary input, which in turn improves system performance including accurate and repeatable fault indications and eliminates the need for multiple hardware versions (use same design for multiple nominal voltage inputs). This reduces efforts in design, testing, manufacturing and field support. In this TI Design, four input channels are configured as group isolated inputs to minimize cost per channel. The binary inputs are isolated from the system interface using digital isolators with external isolated power or digital isolators with an integrated power converter.

### 2.1 Block Diagram

The wide input improved accuracy BIM is based on a digital isolator with integrated power or external power and an MCU with an internal ADC. Using an MCU simplifies the design improving system performance.

The BIM TI Design has the following hardware options:

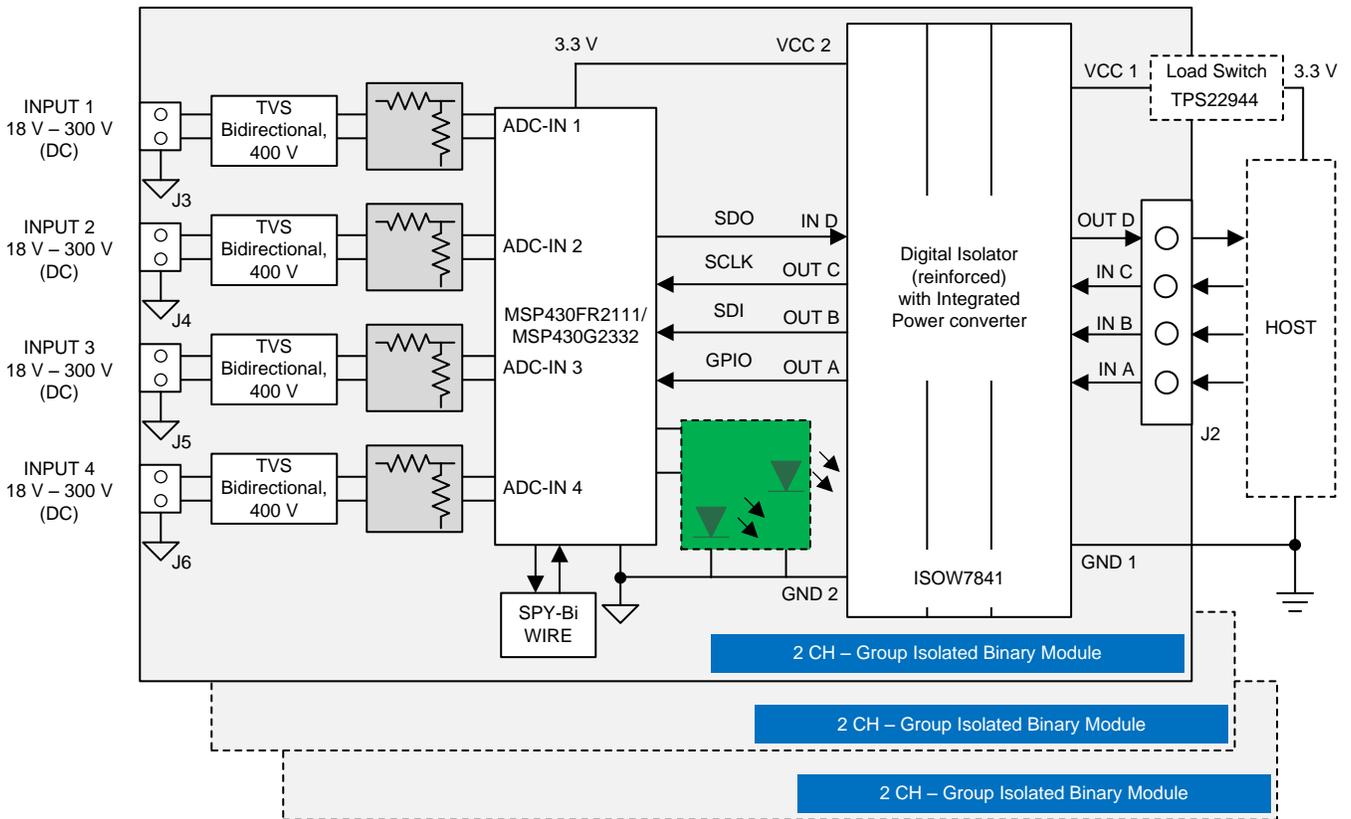
- Four-channel DC BIM with integrated power converter-based digital isolator ISOW7841 and MSP430FR2111 MCU
- Four-channel DC BIM with integrated power converter-based digital isolator ISOW7841 and MSP430G2332 MCU
- Four-channel DC BIM with digital isolator ISO7741, transformer driver-based isolated power supply and MSP430G2332 MCU
- Two-channel AC/DC BIM with integrated power converter-based digital isolator ISO7841 and MSP430G2332 MCU

The customer can choose the design architecture based on the binary input type and the host interface requirement.

### 2.1.1 Four-Channel DC BIM With MSP430FR2111 or MSP430G2332 MCU and ISOW7841

图 1 shows a four-channel DC BIM with the following features:

- Digital isolator ISOW7841 with integrated V power converter
- MSP430FR2111 or MSP430G2332 MCU for processing the binary input and communicating the measured values to the host
- TPS22944 for overload protection of BIM during output short or overload
- Terminals for connecting the binary inputs
- Connector for interfacing BIM to the host



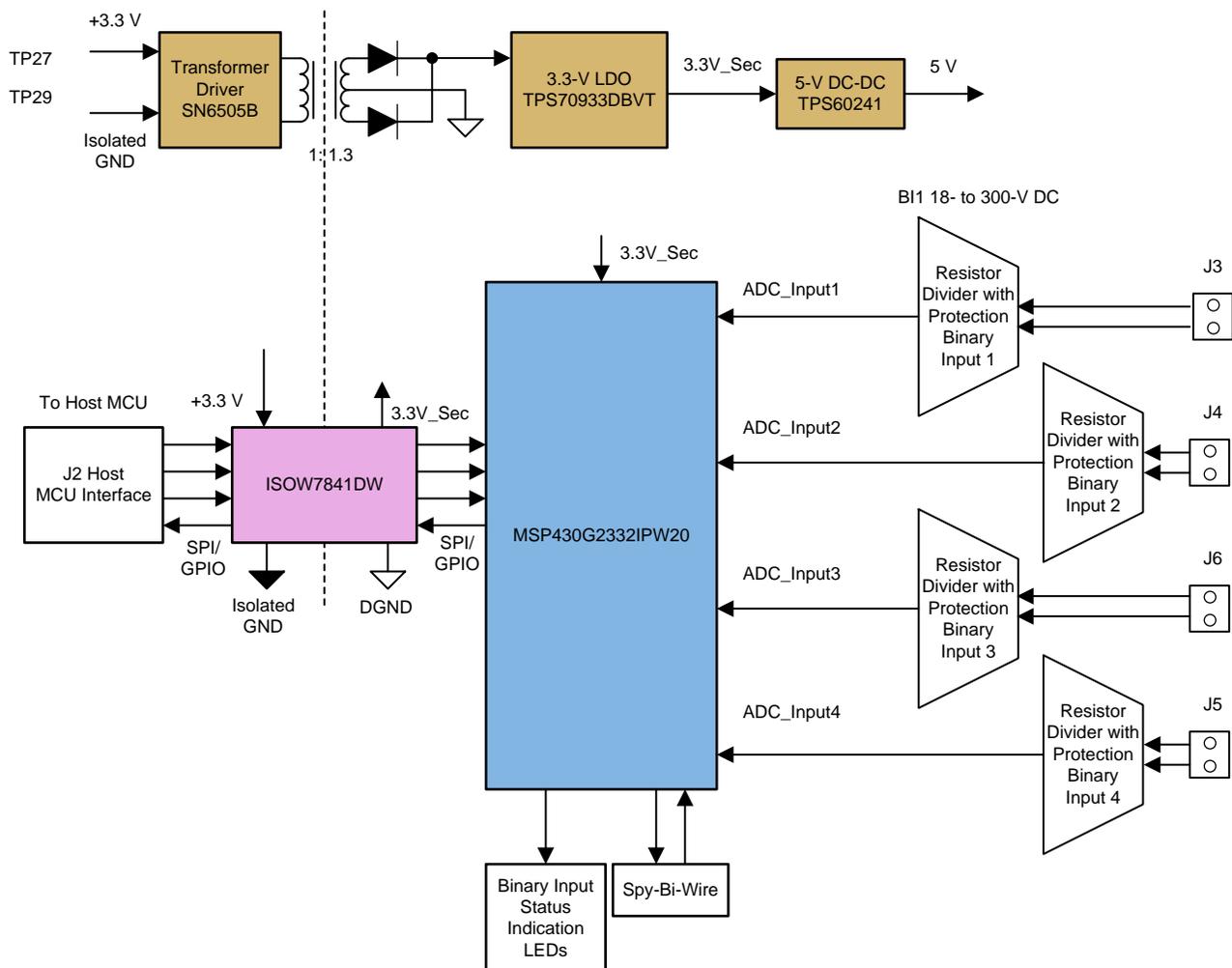
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图 1. Four-Channel DC BIM With MCU and ISOW7841 Integrated Power Converter

### 2.1.2 Four-Channel DC BIM With MSP430G2332 and Digital Isolator

图 2 shows a four-channel DC BIM with the following features:

- Isolated power supply using the transformer driver SN6505B
- Signal isolation using the digital isolator ISO7741
- MSP430G2332 MCU for processing the binary input and communicating the measured values to the host
- LEDs for binary input status indication
- Terminals for connecting the binary inputs
- Connector for interfacing BIM to the host



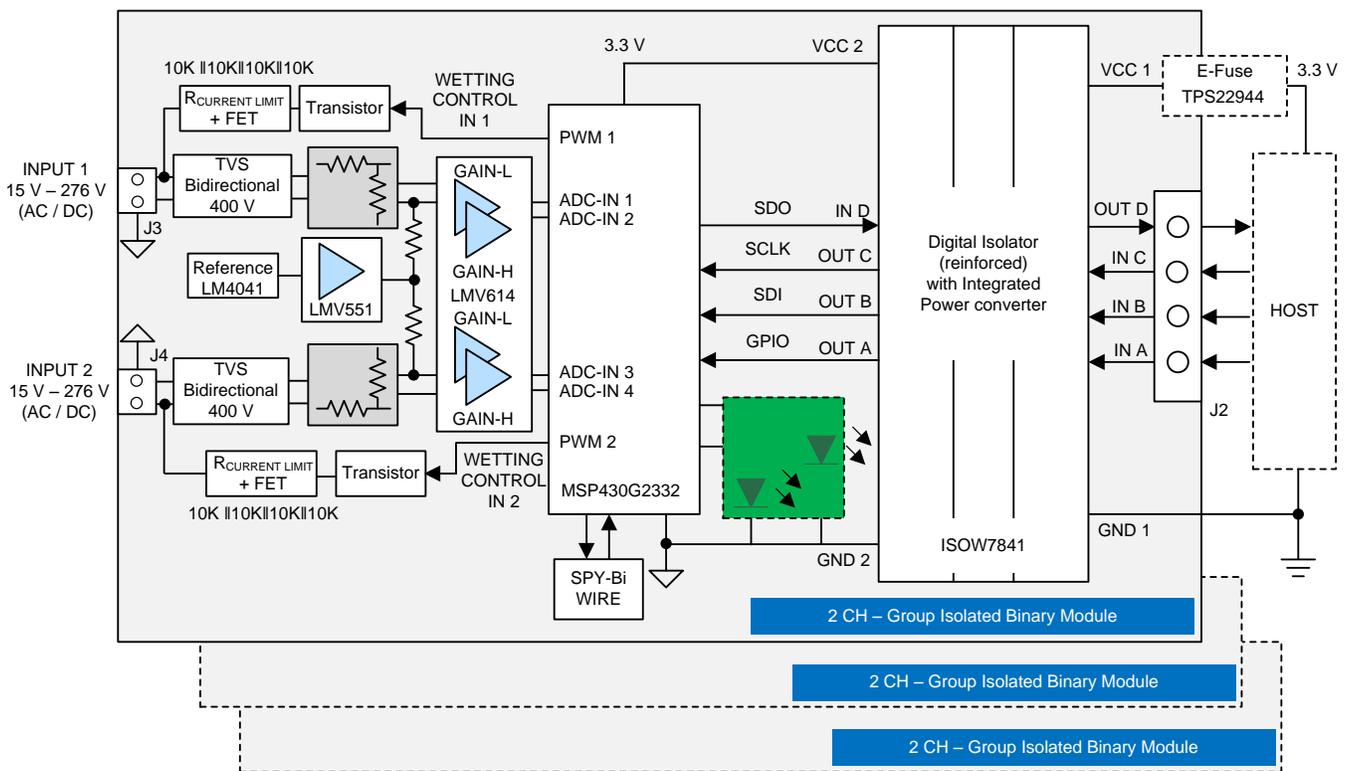
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图 2. Four-Channel DC BIM With MSP430G2332 and ISO7741 With Transformer Driver

### 2.1.3 AC/DC BIM With ISOW7841

图 3 shows a two-channel AC or DC input BIM with the following features:

- Integrated power converter with the digital isolator ISOW7841
- Op amp for providing two gains for improved accuracy LMV614
- Reference LM4041 with buffer LMV551 for level shifting the input to unipolar ADC internal to MCU
- MSP430G2332 MCU for processing the binary input and communicating the measured values to the host
- LEDs for binary input status indication
- Terminals for connecting the binary inputs
- Connector for interfacing binary BIM to the host



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图 3. AC/DC BIM With ISOW7841 Integrated Power Converter

### 2.1.4 MCU

The following subsections detail the MCU used and its configuration.

#### 2.1.4.1 MSP430G2332 for AC/DC BIM

The MSP430G2332 ultra-low-power mixed signal MCU with an internal 10-bit SAR ADC is configured to measure a two-channel input, AC or DC, with two gains for each input in this TI Design. The MCU is used to sample the analog input to compute the binary input amplitude and to communicate the computed amplitude values to the host through SPI, I<sup>2</sup>C, or GPIO. The MCU is also used to control the wetting current and use LEDs to indicate system functionality.

#### 2.1.4.2 **MSP430G2332 for DC BIM**

The MSP430G2332 ultra-low-power mixed signal MCU with 4KB non-volatile memory and an internal 10-bit SAR ADC is configured to measure a four-channel DC input in this TI Design. The MCU is used to sample the analog input to compute the binary input amplitude and to communicate the computed DC values to the host through SPI, I<sup>2</sup>C, or GPIO.

#### 2.1.4.3 **MSP430FR2111 for DC BIM**

The MSP430FR2111 ultra-low-power mixed signal MCU with a 4KB FRAM and an internal 10-bit SAR ADC is configured to measure a four-channel DC input in this TI Design. The MCU is used to sample the analog input to compute the binary input amplitude and to communicate the computed DC values to the host through SPI, I<sup>2</sup>C, or GPIO.

#### 2.1.5 **Digital Isolator With Integrated Power ISOW7841**

The BIM is isolated from the host interface using a digital isolator with an integrated power converter. The ISOW7841 device is used in this TI Design to provide the interface and the power isolation. High Efficiency and Low Emission Isolated Power with Integrated Quad Channel Digital Isolator has been used in this TI design to provide the interface and the power isolation

#### 2.1.6 **Digital Isolator With External Isolated Power**

Alternative approach to isolated the BIM from the host is to use digital isolator and isolated power generated using transformer driver.

The ISO7741 device is used to isolate the BIM from the host. The isolator is configured in SPI. The power converter provides up to 0.5 W of power with high efficiency configured for 3.3-V input and 3.3-V output. The SN6505B and LDO TPS70933 LDO are used to generate the isolated power supply for the BIM.

The High-Speed, Low-Power, Robust EMC Quad-Channel 3/1 Digital Isolator is used to isolate the BIM from the host. The isolator is configured in SPI configuration. The power converter provides up to 0.5-W power with high efficiency configured for 3.3-V input and 3.3-V output. The Low-Noise 1-A Transformer Driver for Isolated Power Supplies, Internal Clock-160kHz is used to generate the isolated power supply for the BIM.

#### 2.1.7 **Signal Conditioning for AC/DC BIM**

The signal conditioning circuit for AC/DC BIM consists of the following:

- Potential divider and input protection
- Gain amplifier and reference for level shifting the input
- Wetting current control circuit for generating the wetting current for BIM

For more information on potential divider and wetting current control, see the [TIDA-00809](#) design.

### 2.1.8 Programming

The two-wire interface is made up of the SBWTCK (Spy-Bi-Wire™ test clock) and SBWTDIO (Spy-Bi-Wire test data I/O) pins. The SBWTCK signal is the clock signal and is a dedicated pin. In normal operation, this pin is internally pulled to ground. The SBWTDIO signal represents the data and is a bidirectional connection. To reduce the overhead of the two-wire interface, the SBWTDIO line is shared with the RST/NMI pin of the device. For more details, see Section 1.2.1.3 of the user's guide [MSP430™ Programming With the JTAG Interface](#) (SLAU320).

## 2.2 Highlighted Products—System Design

This section describes the TI products used in this TI Design with design calculations.

### 2.2.1 Binary Input application requirements

#### 2.2.1.1 Wetting or Auto Burnishing

The binary inputs sense a change of state of the external device. When these external devices are located in a harsh industrial environment (either outdoor or indoor), their contacts can be exposed to various types of contamination. Normally, there is a thin film of insulating sulfidation, oxidation, or contaminants on the surface of the contacts, sometimes making it difficult or impossible to detect a change of the state.

This film must be removed to establish circuit continuity; an impulse of higher than normal current can accomplish this. The contact inputs with auto-burnish create a high-current impulse when the threshold is reached to burn off this oxidation layer as maintenance to the contacts. Afterwards, the contact input current is reduced to a steady-state current. Contact inputs with auto-burnishing allow currents up to 50 mA at the first instance when the change of state was sensed. Then, within 25 to 50 ms, this current is slowly reduced to 5 mA. The 50-mA peak current burns any film on the contacts, allowing for proper sensing of state changes.

#### 2.2.1.2 EMC—Transient Overvoltage Stress

In industrial applications, lightning strikes, power source fluctuations, inductive switching, and electrostatic discharge (ESD) can cause damage to binary inputs by generating large transient voltages. The following tests have been considered in this TI Design:

- IEC 61000-4-2 ESD
- IEC 61000-4-4 EFT
- IEC 61000-4-5 Surge
- IEC 61000-4-6 Immunity to radio frequency-induced signals
- IEC 61000-4-12 Ring wave immunity
- IEC 61000-4-18 Damped oscillatory waves immunity

The level of protection can be further enhanced when using external clamping devices such as TVS diodes. The transients are clamped instantaneously (< 1 ns) and the damaging current is diverted away from the protected device.

#### 2.2.1.3 EMI Conducted and Radiated Emissions as per EN55022 Class A

The emission test that are specified in the standard are as follows:

- Conducted Emission (CE) Class A as per EN55022
- Radiated Emission (RE) Class A as per EN55022 at a distance of 10 meters

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注: Add 10 dB( $\mu$ V/m) when testing the performance in quasi peak, with the DUT placed at a distance of 3 meters.

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#### **2.2.1.4 Group Isolated Two-Channel, Wide AC/DC BIM TI Design Advantages**

Advantages of the AC/DC BIM include:

- Using a digital isolator with integrated power simplifies the system design and increases reliability
- Cost-optimized solution
- Allows for measurement of wide AC/DC input voltage
- Indicates binary input status using LEDs
- Uses MCU to allow flexibility in terms of input voltage processing and wetting current control
- Reduces measurement error that could be caused due to bridge rectifier at the input
- Improves voltage input measurement accuracy by using multiple gains

#### **2.2.1.5 Group Isolated Four-Channel, Wide DC BIM TI Design Advantages**

Advantage of the DC BIM include:

- Using a digital isolator with integrated power simplifies the system design and increases reliability
- Cost-optimized solution
- Indicates binary input status using LEDs
- Allows for measurement of wide DC input voltage for up to four channels
- Cost- and size-optimized design using the MSP430G2332 or MSP430FR2111 MCU
- Using a microprocessor improves measurement accuracy

## 2.2.2 MCU

The following subsections detail the MCU interface as used in this TI Design.

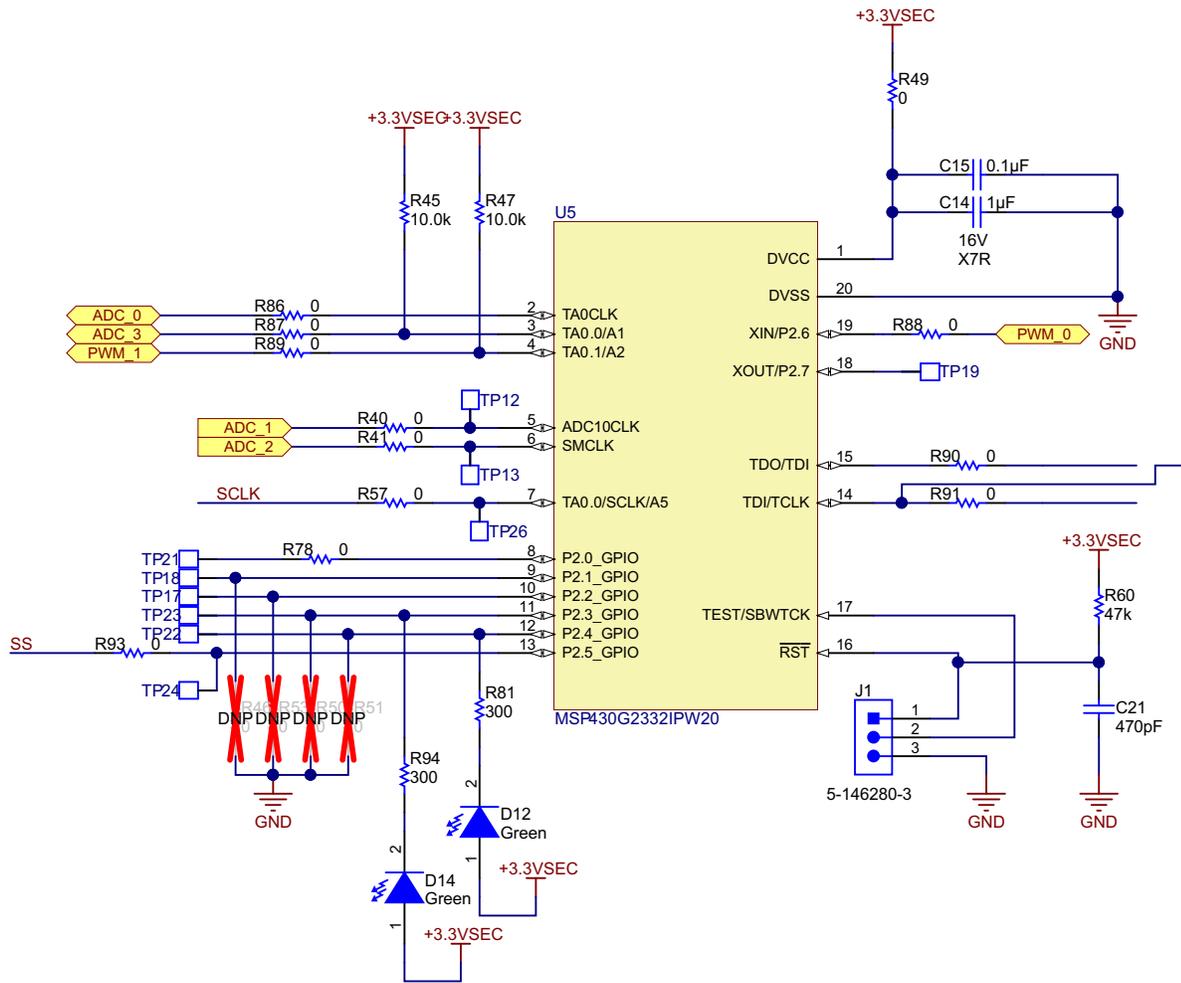
### 2.2.2.1 MSP430G2332 for AC/DC or DC BIM

表 3 details the MCU configuration to interface with the host through the digital isolator.

表 3. MCU to Digital Interface for AC/DC or DC BIM With MSP430G2332

MCU PINS	CONFIGURATION	ALTERNATIVE	COMMENTS
Pin 7, P1.5/TA0.0/SCLK/A5/TMS	SCLK	GPIO	The MCU pin configuration depends on the implementation of the BIM functionality
Pin 13, P2.5	SS	GPIO	
Pin 14, P1.6/TA0.1/SDO/SCL/A6/TDI/TCLK	SDO	GPIO/SCK	
Pin 15, P1.7/SDI/SDA/A7/TDO/TDI	SDI	GPIO/SDA	

图 4 shows the MSP430G2332 configured for measuring AC or DC analog inputs and LEDs for binary input status indication and interfacing with digital isolator



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图 4. MSP430G2332 MCU Configuration Schematics With Interface to Digital Isolator

The MSP430G2x32 series of MCUs are ultra-low-power mixed signal MCUs with built-in 16-bit timers and built-in communication capability using the universal serial communication interface. The MSP430G2x32 series have 10-bit ADCs (see the [MSP430G2332](#) product page).

Features:

- Low supply voltage range: 1.8 to 3.6 V
- Universal serial interface (USI) supporting SPI and I<sup>2</sup>C
- 10-Bit 200-ksps ADC With Internal Reference, Sample-and-Hold, and Autoscan (MSP430G2x32 Only)
- Brownout detector
- On-chip emulation logic with Spy-Bi-Wire interface
- Package options TSSOP: 20 pin

### 2.2.2.2 **MSP430FR2111 for DC BIM**

表 4 details the MCU configuration to interface with the host through the digital isolator.

表 4. MCU to Digital Interface for DC BIM With FRAM-Based MCU

MCU PINS	CONFIGURATION	ALTERNATIVE	COMMENTS
Pin 9, P2.1/TB0.2	GPIO	—	The MCU pin configuration depends on the implementation of the binary BIM functionality
Pin 10, P2.0/TB0.1/COOUT	GPIO	—	
Pin 11, P1.7/UCA0TXD/UCA0SIMO	GPIO	UART transmit	
Pin12, P1.6/UCA0RXD/UCA0SOMI	GPIO	UART receiver	

MSP430FR211x devices are an expansion of the MSP430 MCU value line. Ferroelectric random access memory (FRAM) is a non-volatile memory that combines the speed, flexibility, and endurance of SRAM with the stability and reliability of flash, all at lower total power consumption (see the [MSP430FR2111](#) product page).

Features:

- MSP430FR2111 with 3.75 KB of program FRAM + 1KB of RAM
- Embedded MCU 16-bit RISC architecture up to 16 MHz
- Wide supply voltage range: 1.8 to 3.6 V (Operation voltage is restricted by SVS levels)
- Low-power FRAM Up to 3.75 KB of non-volatile memory
- Built-in error correction code (ECC)
- Enhanced serial communications enhanced USCI A (eUSCI\_A) supports UART, IrDA, and SPI
- High-performance analog eight-channel 10-bit ADC, 200 ksps
- Package options 16-pin: TSSOP (PW16)

### 2.2.2.3 Input Voltage Calculations for AC/DC BIM

表 5 提供了用于计算可以施加到 AC 或 DC BIM 的最大 DC 或 AC 电压的计算，具有两个增益。

**表 5. Maximum Input Voltage for AC/DC BIM**

VOLTAGE INPUT	CALCULATIONS	VALUES
Maximum DC input allowed	DC offset in ADC counts	511
	ADC range in counts	$1023 - 511 = 512$
	Resistor divider ratio	$301.1 \text{ k}\Omega / 1.1 \text{ k}\Omega = 273.72$
	DC input ADC reference span	$\text{ADC}_{\text{REF}} = 1.65 \text{ V}$
	Maximum input voltage	$\text{ADC}_{\text{REF}} \times \text{Resistor divider ratio} = > 300 \text{ V}$
Maximum AC input allowed	DC offset in ADC counts	511
	Peak ADC range in counts	$1023 - 511 = 512$
	RMS ADC range in counts	$512 / 1.414 = 362$
	Resistor divider ratio	$301.1 \text{ k}\Omega / 1.1 \text{ k}\Omega = 273.72$
	AC RMS ADC reference span	$\text{Avg}_{\text{REF}} = 1.65 \text{ V} / 1.414 = 1.1668$
	Maximum input voltage	$\text{Avg}_{\text{REF}} \times \text{Resistor divider ratio} = > 300 \text{ V}$

### 2.2.2.4 Converting ADC Counts to Input Voltage for AC/DC BIM

表 6 提供了用于将测量的 ADC 计数转换为施加的输入电压的计算。施加的输入电压可能是 AC 或 DC。

**表 6. Converting ADC Counts to Input Voltage for AC/DC BIM**

ADC COUNT TO VOLTAGE	CALCULATIONS	VALUES
DC input low gain	$\text{ADC}_{\text{REF}}$	1.65
	Maximum input	450 V
	Gain factor	1
	Max ADC count for DC input	512
	DC voltage equivalent for one ADC count	$\text{Maximum input} / (\text{ADC count} \times \text{Gain factor}) = 0.878 \text{ V}$
DC input high gain	$\text{ADC}_{\text{REF}}$	1.65
	Maximum input	450 V
	Gain factor	3.4
	Max ADC count	512
	DC voltage equivalent for one ADC count	$\text{Maximum input} / (\text{ADC count} \times \text{Gain factor}) = 0.2582$
AC input low gain	$\text{ADC}_{\text{REF}} - \text{peak}$	1.65
	Maximum input	315 V
	Gain factor	1
	Max ADC count	$512 / 1.414 = 362$
	RMS voltage equivalent for one ADC count	$\text{Maximum input} / (\text{ADC count} \times \text{Gain factor}) = 0.870$
AC input high gain	$\text{ADC}_{\text{REF}} - \text{peak}$	1.65
	Maximum input	315 V
	Gain factor	3.4
	Max ADC count for RMS input	$512 / 1.414 = 362$
	RMS voltage equivalent for one ADC count	$\text{Maximum input} / (\text{ADC count} \times \text{Gain factor}) = 0.260$

### 2.2.2.5 Calculations for DC BIM

表 7 提供了计算最大 DC 输入电压并将 ADC 计数转换为施加的输入电压的计算。

表 7. Calculation for DC BIM

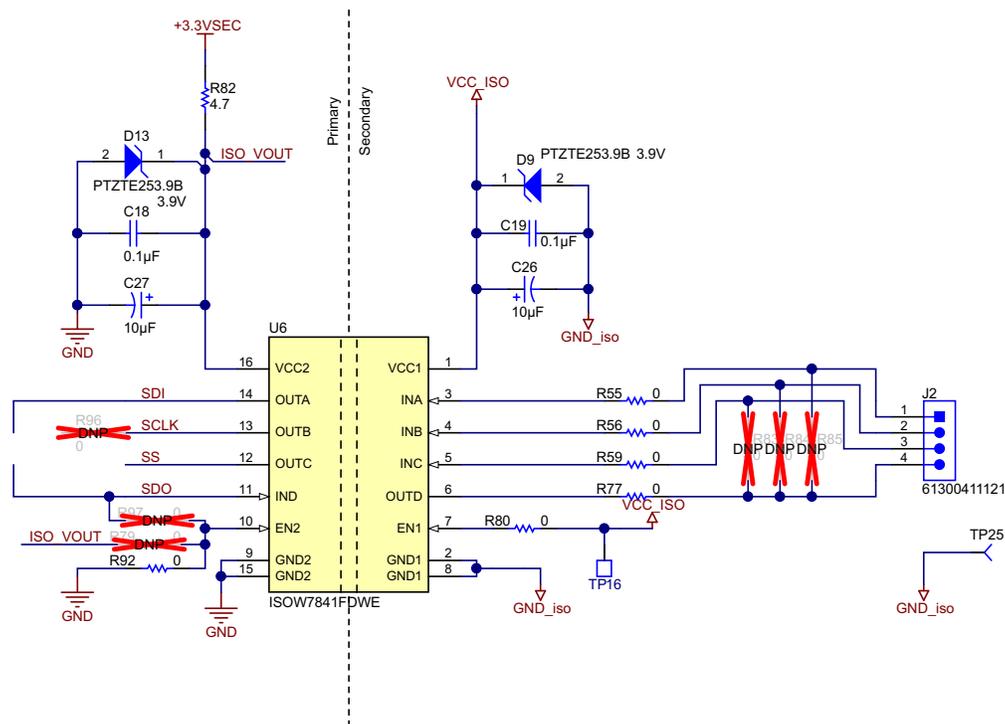
ADC COUNT TO VOLTAGE	CALCULATIONS	VALUES
Maximum DC input allowed	ADC range in counts	0 to 1023
	Resistor divider ratio	$303.16 \text{ k}\Omega / 3.16 \text{ k}\Omega = 95.93$
	ADC reference	$\text{ADC}_{\text{REF}} = 3.3 \text{ V}$
	Maximum input voltage	$\text{ADC}_{\text{REF}} \times \text{Resistor divider ratio} = 315 \text{ V}$
Converting ADC count to voltage	VCC	3.3 V
	Maximum input	315 V
	ADC count for maximum input	1023
	DC Voltage equivalent for one ADC count	$\text{Maximum input} / \text{ADC count} = 0.3076 \text{ V}$

注: If the overall input voltage span is reduced by increasing the voltage output across the resistor divider, the accuracy at lower voltage can be improved

### 2.2.3 ISOW7841—Digital Isolator With Integrated Power

The ISOW7841 device has three forward and one reverse-direction channels and is interfaced to the host and the onboard binary input measurement input as shown in 图 5.

图 5 显示了 ISOW7841 设备配置为 SPI 以隔离 BIM 来自主机。ISOW7841 具有集成的数字隔离器和电源转换器，简化了设计。



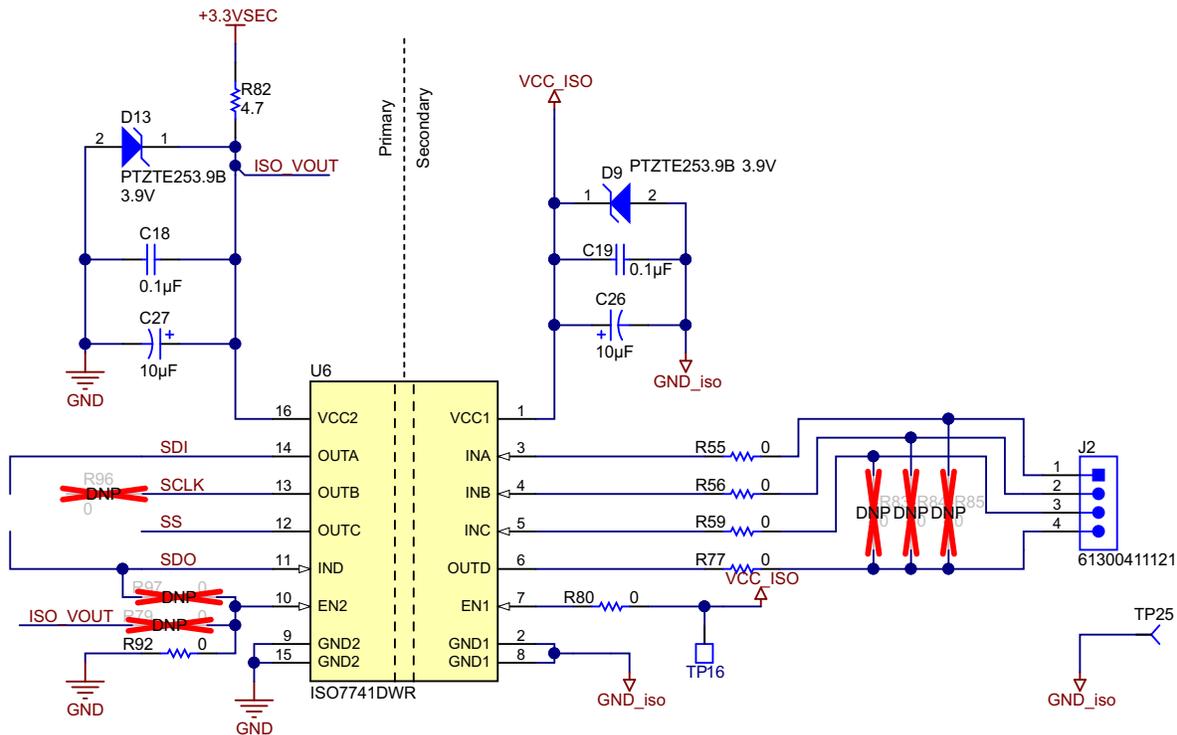
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图 5. ISOW7841 Configured for Integrated Power and Data Interface

### 2.2.4 Digital Isolator With External Isolated Power

The ISO7741 device has three forward and one reverse-direction channels and is interfaced to the host and the onboard binary input measurement input as shown in 图 6.

图 6 shows the ISO7741 configured for SPI for isolating the BIM from the host. The required isolated power is generated using the transformer driver and LDO.



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图 6. ISO7741 Configured for Digital Interface With External Isolated Power

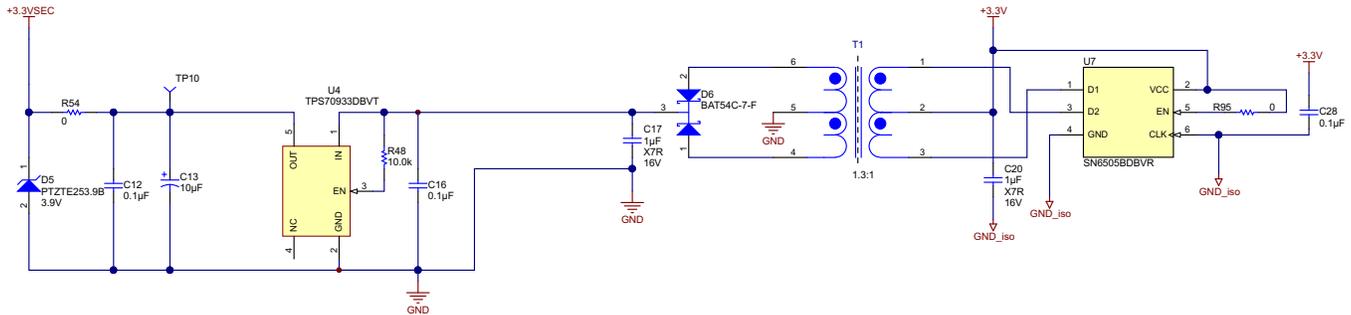
The ISO774x devices are high-performance, quad-channel digital isolators with 5000- $V_{RMS}$  (DW package) isolation ratings per UL 1577. This family of devices has reinforced insulation ratings according to VDE, CSA, TUV, and CQC. The ISO7741 device has three forward and one reverse-direction channels (see the ISO7741 product page).

Features:

- Signaling rate: Up to 100 Mbps
- Wide supply range: 2.25 to 5.5 V
- Wide temperature range:  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$
- Low power consumption: 1.5 mA typical per channel at 1 Mbps
- Low propagation delay: 10.7 ns typical (5-V supplies)
- High CMTI:  $\pm 100$  kV/ $\mu\text{s}$  typical with isolation barrier life (> 40 years)
- Wide-SOIC (DW-16)

### 2.2.4.1 Isolated Power Using SN6505B and LDO TPS70933

图 7 shows the isolated power supply circuit using the transformer driver and LDO.



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图 7. Transformer Driver-Based Isolated Power for Digital Isolator Interface

The SN6505 is a low-noise, low-EMI push-pull transformer driver, specifically designed for small form factor, isolated power supplies. It drives low-profile, center-tapped transformers from a 2.25- to 5-V DC power supply. The SN6505 includes a soft-start feature that prevents high inrush current during power up with large load capacitors. The SN6505 is available in a small 6-pin SOT23/DBV package. The device operation is characterized for a temperature range from  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  (see the [SN6505B](#) and [TPS709](#) product pages).

Features:

- Push-pull driver for transformers
- Wide input voltage range: 2.25 to 5.5 V
- High output drive: 1 A at a 5-V supply
- Spread spectrum clocking
- Synchronization of multiple devices with external clock input
- Slew-rate control

Alternatively, consider the [SN6501](#) Low-Noise, 350-mA, 410-kHz Transformer Driver for isolated power supply generation.

### 2.2.5 Signal Conditioning

This TI Design has two gains to measure AC or DC input voltage up to 300 V. The gains are provided using operational amplifiers (op amps). The gains are set to 1 and 3.4. The gains can be adjusted based on the input range and the accuracy requirement.

#### 2.2.5.1 Gain Amplifier LMV614

The LMV614 devices are quad low-voltage, low-power op amps. They are designed specifically for low-voltage, general-purpose applications. Other important product characteristics are rail-to-rail input or output, low supply voltage of 1.8 V, and a wide temperature range (see the [LMV614](#) product page).

### 2.2.5.2 Reference LM4041

The LM4041-N precision voltage reference is available in SOT-23 surface-mount packages. The advanced design of the LM4041-N eliminates the need for an external stabilizing capacitor while ensuring stability with any capacitive load, thus making the LM4041-N easy to use. Further reducing the design effort is the availability of a fixed (1.225 V) and adjustable reverse breakdown voltage. The minimum operating current is 60  $\mu$ A for the LM4041-N 1.2 and the LM4041-N ADJ. Both versions have a maximum operating current of 12 mA (see the [LM4041-N](#) product page).

### 2.2.5.3 Reference Buffer LMV551

The LMV551 is a high-performance, low-power op amp. They feature 3 MHz of bandwidth while consuming only 37  $\mu$ A of current per amplifier, which is an exceptional bandwidth to power ratio in this op amp class. These ultra-low-power amplifiers are unity gain stable and provide an excellent solution for ultra-low-power applications requiring a wide bandwidth (see the [LMV551](#) product page).

### 2.2.6 Other Hardware Options

The following subsections provide options for improving the performance of the digital isolator with the integrator power converter. In applications requiring multiple DC voltage for operation, a low ripple 3.3- to 5-V DC-DC converter can be used. During an output load short condition, the input current drawn is  $\approx$  130 mA. This current is drawn from the power source continuously. To protect the BIM under this condition, a load switch can be used. During output overload the output of the ISOW784x droops. To overcome the devices malfunction during voltage droop, the voltage supervisor can be used.

#### 2.2.6.1 3.3- to 5-V High-Efficiency DC-DC Converter TPS60241

The TPS60241 devices are a family of switched capacitor voltage converters, ideally suited for voltage-controlled oscillator (VCO) and phase-locked loop (PLL) applications that require low noise and tight tolerances. Its dual-cap design uses four ceramic capacitors to provide ultra-low output ripple with high efficiency, while eliminating the need for inefficient linear regulators. The TPS60241 works with a 2.7- to 5.5-V input voltage providing a 5-V output. The devices work equally well for low EMI DC-DC step-up conversion without the need for an inductor. The high switching frequency (typical 160 kHz) promotes the use of small surface-mount capacitors, saving board space. The shutdown mode of the converter conserves battery energy (see the [TPS60241](#) product page).

#### 2.2.6.2 Load Switch TPS22944

The TPS22944 load switch protects systems and loads in high-current conditions. The devices contain a 0.4- $\Omega$  current-limited P-channel MOSFET that can operate over an input voltage range of 1.62 to 5.5 V. Current is prevented from flowing when the MOSFET is off. The switch is controlled by an on/off input (ON), which is capable of interfacing directly with low-voltage control signals (see the [TPS22944](#) product page).

表 8 details the selection of load switches based on the power requirements.

**表 8. Load Switch Selection Options**

SERIAL NUMBER	PART NUMBER	DESCRIPTION
1	LM34902	300-mA Current Limited Power Switch
2	TPS2010	0.4-A, 2.7 to 5.5-V, Single High-Side MOSFET Switch IC, No Fault Reporting, Active-Low Enable
3	TPS22946	5.5-V, 0.2-A, 400-m $\Omega$ Selectable Current Limit Load Switch

### 2.2.6.3 Data Interface Selection

TI provides MSP430G23xx and MSP430FR21xx family of cost-optimized small pin count MCUs that are well suited for BIM applications. Based on the interface required, consider the devices listed in 表 9:

表 9. MSP430 MCU Family Devices Selection

INTERFACE TYPE	DEVICES
SPI	MSP430G2332
	MSP430FR2111
	MSP430G2203
I <sup>2</sup> C	MSP430G2332
	MSP430FR2111
	MSP430G2203
UART	MSP430FR2111
	MSP430G2203 or MSP430G2553

### 2.2.7 ISOW7841 Advantages

Two different approaches can be considered for providing isolated power and data interface using TI's digital isolator family.

#### 2.2.7.1 Isolated Interface With Transformer Driver and Digital Isolator

This approach consists of the following blocks that require multiple products as shown in 表 10.

- Digital isolator
- Transformer driver
- Isolation transformer
- LDO

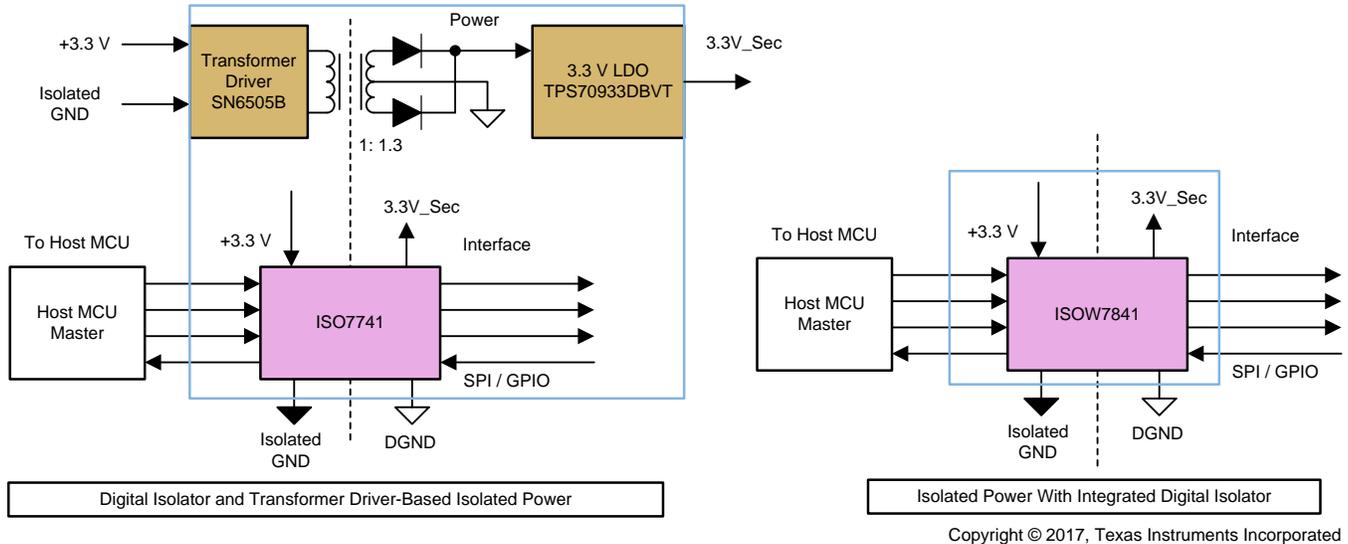
The advantage of this approach is that the module can be a design using any of the following digital isolators or with any of the digital isolator families including devices with reinforced digital isolation or basic digital isolation.

表 10. Digital Isolator Families With External Isolated Power

SERIAL NUMBER	PART NUMBER	DESCRIPTION	INTERFACE TYPE
1	ISO7721	High-Speed, 5000-V <sub>RMS</sub> Dual-Channel Digital Isolators	UART
2	ISO7740	High-Speed, Low-Power, Robust EMC Quad-Channel Digital Isolator	GPIO
3	ISO7841	High-Immunity, 5.7-kV <sub>RMS</sub> Reinforced Quad-Channel 3/1 Digital Isolator, 100Mbps	SPI
4	ISO7840	High-Immunity, 5.7-kV <sub>RMS</sub> Reinforced Quad-Channel 4/0 Digital Isolator, 100 Mbps	GPIO
5	ISO7821	High-Immunity, 5.7-kV <sub>RMS</sub> Reinforced Dual-Channel 1/1 Digital Isolator, 100 Mbps	UART
6	ISO7641	6-kVpk Low-Power Quad Channels, 150-Mbps Digital Isolators	SPI

### 2.2.7.2 Isolated Interface Using ISOW7841

All these components are integrated into one device, simplifying the design as shown in 图 8 and reducing the solution size and optimizing the cost. In applications where the required interface matches with the ISOW784x device family, this solution is recommended.



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图 8. ISOW7841 Integrated Data and Power

The ISOW7841 with integrated power converter provides the following advantages:

- Simplifies system design with increased reliability
- Provides current output > 65 mA with 46% efficiency
- Provides current limit and thermal overload protection
- Lower temperature rise and overall heat dissipation

### 2.2.8 Design and Layout Guidelines for ISOW7841

To help ensure reliable operation at data rates and supply voltages, adequate decoupling capacitors must be located as close to supply pins as possible. The input supply must have an appropriate current rating to support output load and switching at the maximum data rate required by the end application. Because the device has no thermal pad to dissipate heat, the device dissipates heat through the respective GND pins. Ensure that enough copper is present on both GND pins to prevent the internal junction temperature of the device from rising to unacceptable levels.

See Section 12 of the [ISOW784x datasheet](#) for more details (SLLSEY2).

### 2.2.9 Interface With High-Precision ADCs With Serial Interface

The digital isolators ISOW7841 or ISO7741 can be used to interface to ADCs, DACs, or other TI products with SPI. 表 11 provides some of the options for an ADC interface.

表 11. ADC to Interface With Data Acquisition Front-End With ISOW7841

SERIAL NUMBER	TI ADC PART	ADC DESCRIPTION	INTERFACE TYPE
1	ADS8688 or ADS8688A	16-Bit, 500-kSPS, 8-Channel, Single-Supply, SAR ADCs with Bipolar Input Ranges	SPI-compatible interface with daisy-chain
2	ADS8681 or ADS8668	16-bit, 1-MSPS, 5-V SAR ADC with Integrated Analog Front-End and Bipolar Inputs	multiSPI™ interface with daisy-chain
3	ADS8588S	16-Bit, 200-kSPS, 8/6/4 Ch, Simultaneous-Sampling ADCs with Bipolar Inputs on a Single Supply	Serial interface
4	ADS131E08 or ADS131E04 or ADS131E08S	Analog Front-End for Power Monitoring, Control, and Protection	SPI data interface
5	ADS131A04	24-Bit, 128-kSPS, 4-Ch, Simultaneous Sampling, Delta-Sigma ADC	Multiple SPI data interface modes
6	ADS131A02	24-Bit, 128-kSPS, 4-Ch, Simultaneous Sampling, Delta-Sigma ADC	Multiple SPI data interface modes

#### 2.2.9.1 Voltage Supervisor Selection and Options

During an output overload condition, the output of the ISOW7841 reduces proportional to the output current. To ensure the MCU operates within a specified range, an external programmable-delay supervisory circuit can be considered. The TPS3808 has been provided in this TI Design. 表 12 lists other devices to also consider:

表 12. Voltage Supervisor Selections

SERIAL NUMBER	PART NUMBER	DESCRIPTION
1	TPS3836	Nano-power supervisory circuits
2	TPS3837	Nano-power supervisory circuits
3	TPS3838	Nano-power supervisory circuits
4	TPS3839	Ultra-low-power, supply voltage supervisor
5	TPS3820	Voltage monitor with watchdog timer

#### 2.2.9.2 LED Indication for BIM Status

The advantage of using an MCU is the status of the BIM can be shown to the user (annunciator or annunciation). The design allows for LED that can be used for status indication. Based on the design, LEDs can be used to indicate status of individual binary inputs. To drive the LEDs, the options in 表 13 can be used:

表 13. Options to Drive BIM Status LED

SERIAL NUMBER	PART NUMBER	DESCRIPTION
1	CSD17571Q2	30 V, 20 mΩ, SON 2x2 NexFET™ power MOSFET
2	TLC5916	Constant-current LED sink drivers

### 3 Getting Started Hardware

This section provides information on connecting the BIM for functional and performance testing. See TIDA-00847\_Safety\_User\_Guide.docx before connecting the inputs.

#### 3.1 AC/DC BIM

表 14 provides information on the different interface connectors for connecting DC power supply, host interface, and binary inputs (AC or DC).

表 14. AC/DC BIM Connections

FUNCTIONS	INPUT	SIGNAL NAME	PINS
Power connections	Power supply	+3.3V	TP27
		Ground	TP29
Input voltage	Binary input 1	Positive input	J3-1
		Negative input	J3-2
	Binary input 2	Positive input	J4-1
		Negative input	J4-2
Host interface	SPI	SCK	J2-2
		SDI	J2-1
		/CS	J2-3
		SDO	J2-4
		GND	TP25

#### CAUTION

**HIGH VOLTAGE:** Binary input voltage can vary between 20 to 300 V. Ensure the voltage source is switched off while connecting the binary inputs and do not touch the input terminal during testing

### 3.2 DC BIM

表 15 提供有关连接 DC 电源供应、主机接口，和 DC 二进制输入的不同接口连接器的信息。

表 15. DC BIM Connections

FUNCTIONS	INPUT	SIGNAL NAME	PINS
Power connections	Power	+3.3V	TP27
		Ground	TP29
Input voltage	Binary input 1	Positive input	J3-1
		Negative input	J3-2
	Binary input 2	Positive input	J4-1
		Negative input	J4-2
	Binary input 3	Positive input	J6-1
		Negative input	J6-2
	Binary input 4	Positive input	J5-1
		Negative input	J5-2
Host interface	SPI	SCK	J2-2
		SDI	J2-1
		/CS	J2-3
		SDO	J2-4
		GND	TP25

#### CAUTION

**HIGH VOLTAGE:** Binary input voltage can vary between 20 to 300 V. Ensure the voltage source is switched off while connecting the binary inputs and do not touch the input terminal during testing.

## 4 Testing and Results

Note the following test conditions for performance measurement of the BIM:

- All measurements in this section are RMS values.
- The source uncertainty is  $\pm 0.1\%$ .
- Take care to not open the current source outputs during testing.
- The inputs must be connected with the AC voltage and current source output programmed to zero and the output switched OFF.
- DC offset was performed and the DC values were subtracted during RMS computation.
- The 30-V DC input was connected for all the EMC tests.
- 110 V was connected for CE.

表 16 details the tests done on the BIM side (VCC2 and GND2 side of the digital isolator) and the source.

**表 16. Power Source Used for Testing**

TESTS	TEST PORT	POWER SOURCE	COMMENTS
IEC61000-4-2	Binary inputs	Battery source regulated to 3.6 V	Test 1: ESD power earth was referenced to GND1
IEC61000-4-4, IEC61000-4-5	Binary inputs	DC voltage source (table top) 3.45 V	EFT and surge generator power earth was referenced to GND1
IEC61000-4-6	Binary inputs	Battery source regulated to 3.6 V	Test equipment influences DC power supply (source) performance
IEC61000-4-12, IEC61000-4-18	Binary inputs	Battery source regulated to 3.6 V	Ring wave generator power earth was referenced to GND1
EN55022 CE and RE	Binary inputs	Battery source regulated to 3.6 V	Looking for emission from the BIM only

## 4.1 Test Setup

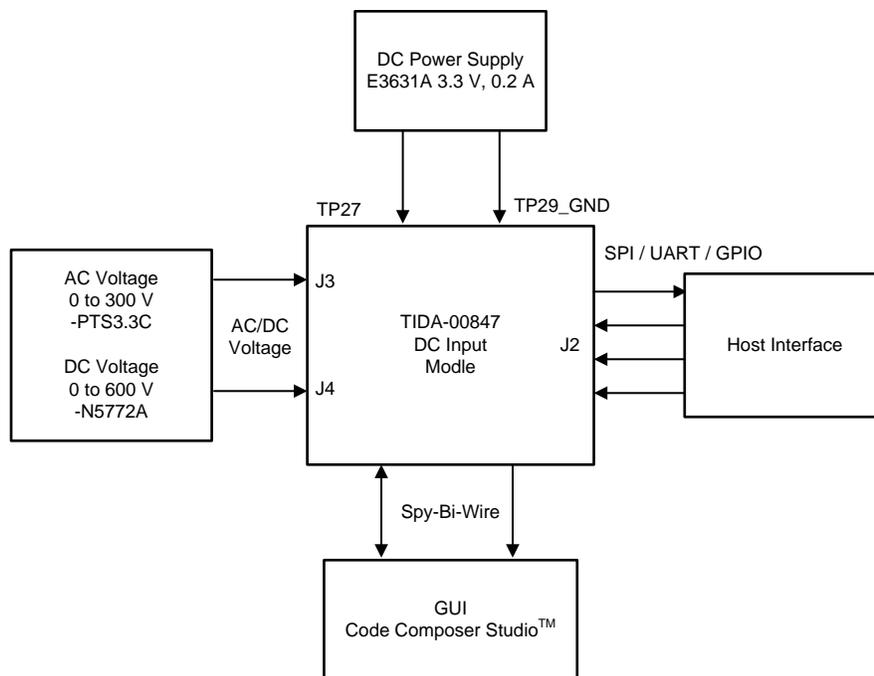
图 9 提供了有关用于 AC/DC BIM 的功能性和性能测试的设置的详细信息。

### 4.1.1 AC/DC BIM Connection

测试 BIM 的设置包括以下内容：

- DC 电源 (3.3 V, 200 mA)
- AC 或 DC 输入电压 (20 到 300 V)
- TIDA-00847 AC/DC BIM 带有 ISOW7841
- GUI 用于固件升级和数据捕获

注： 在测试过程中，请确保输入不超过规定的范围，以确保正确操作。



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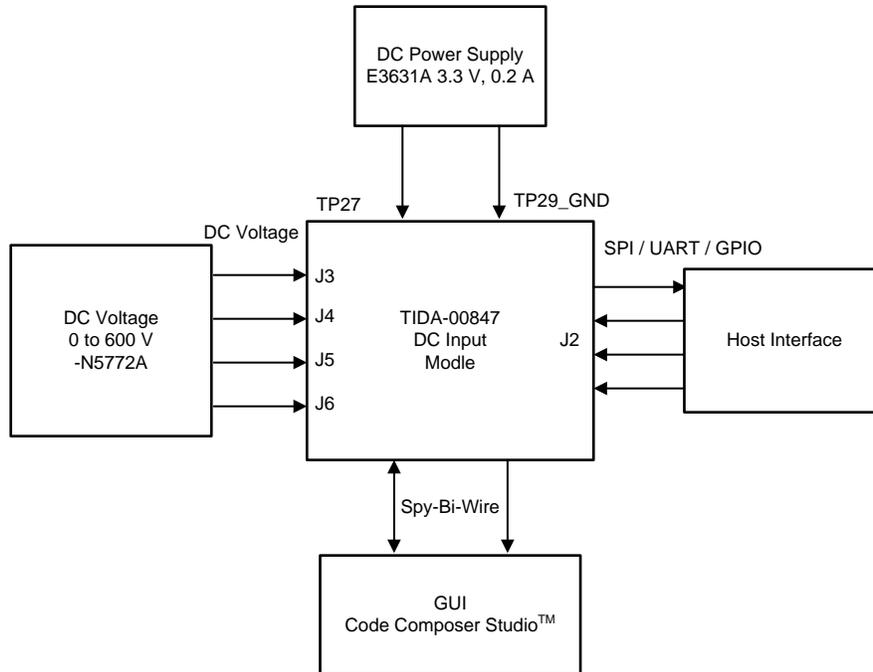
图 9. Test Setup for AC/DC BIM Performance Testing

### 4.1.2 DC BIM Connection

The setup to test the BIM consists of the following:

- DC power supply (3.3 V, 200 mA)
- DC input voltage (20 to 300 V)
- TIDA-00847 DC BIM with ISOW7841 or ISO7741

注: While testing, ensure the inputs do not exceed the range specified for proper operation.



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图 10. Test Setup DC BIM Performance Testing

## 4.2 Functional Testing

表 17 提供有关在不同功能测试中对 BIM 进行测试的信息。

表 17. Functional Test Observations

PARAMETER	SPECIFICATION	MEASUREMENT
Isolated supply ISOW7841 output	3.3 V	3.36
Output ripple on isolated supply for ISO7841	100 mV	≈ 100 mV
DC current from supply under short circuit on VISO (in mA)	135	< 135
Transformer driver based isolated supply	3.3 V	3.32 V
3.3- to 5-V DC-DC converter	5 V	5 V
ISOW7841-based digital isolator functionality	Communication functionality	OK
ISO7741 Digital isolator functionality	Communication functionality	OK
MCU programming	Spy-Bi-Wire	OK
LED indication	Port toggling	OK
Potential divider ration for DC input BIM	300:2.2	OK
Reference output	1.65 V	1.645
Op-amp gain for AC/DC measurement	×1 , ×3.4	OK
DC input measurement accuracy	±3% of measured value ± 1 V	OK

### 4.2.1 ISOW7841 Load Regulation Testing

负载调节测试是通过将输出负载从 20 到 100 mA 和输入为 3.3 V 施加在功率连接器的输入端。表 18 提供了负载调节的测试结果。

表 18. ISOW7841 Load Regulation Test<sup>(1)</sup>

INPUT VOLTAGE (V)	INPUT I (SUBTRACTING NO LOAD I) (A)	POWER	OUTPUT VOLTAGE (V)	OUTPUT CURRENT (A)	POWER (W)	EFFICIENCY	OBSERVATIONS	LOAD in R
3.3	0.057	0.188	3.340	0.022	0.073	39.064%	—	150
3.3	0.081	0.267	3.340	0.033	0.112	41.734%	—	100
3.3	0.101	0.333	3.364	0.044	0.148	44.409%	—	75
3.3	0.124	0.409	3.364	0.055	0.185	45.215%	—	150 100
3.3	0.144	0.475	3.364	0.067	0.225	47.289%	—	150 75
3.3	0.168	0.554	3.364	0.078	0.262	47.268%	—	100 75
3.3	0.184	0.607	3.364	0.085	0.285	46.876%	—	39
3.3	0.262	0.865	3.380	0.122	0.413	47.772%	—	27
3.3	0.254	0.838	3.043	—	—	—	Overcurrent clamp	22

<sup>(1)</sup> No load input current: 0.026 A

Observation: Load regulation observed was < ±1%.

### 4.2.2 ISOW7841 Line Regulation (Input versus Output Voltage Variation) Testing

Line regulation was tested by varying voltage from 3.6 V to 2.3 V with an approximate 80-mA load at the output of the power connector. 表 19 provides the test results for line regulation.

表 19. Line Regulation (Input versus Output Voltage Variation) and UVLO

VOLTAGE (V)		CURRENT (A)		EFFICIENCY	LOAD in RR	SUPPLY I (A)	OBSERVATIONS
INPUT	OUTPUT	OUTPUT I	INPUT I				
3.6	3.363	0.086	0.174	49.55%	39	0.200	—
3.3	3.360	0.086	0.184	46.82%	—	0.210	—
3.0	3.373	0.086	0.201	43.02%	—	0.227	—
2.7	3.380	0.086	0.229	37.84%	—	0.255	—
2.6	3.330	0.085	0.231	36.96%	—	0.257	UVLO recover
2.5	3.200	0.082	0.222	36.96%	—	0.248	—
2.4	3.000	0.076	0.214	35.94%	—	0.240	—
2.3	0	—	—	—	—	0	UVLO

Observation: Line regulation observed was  $< \pm 3$  mV/V.

### 4.2.3 ISOW7841 Ripple Measurement

图 11 shows DC output ripple in mV on isolated supply (pkpk) with a 20-MHz bandwidth,  $C_{LOAD} = 20 \mu F$ ,  $I_{ISO} = 80$  mA. The measurements were done near to the load, away from the ISOW7841 power output pins.

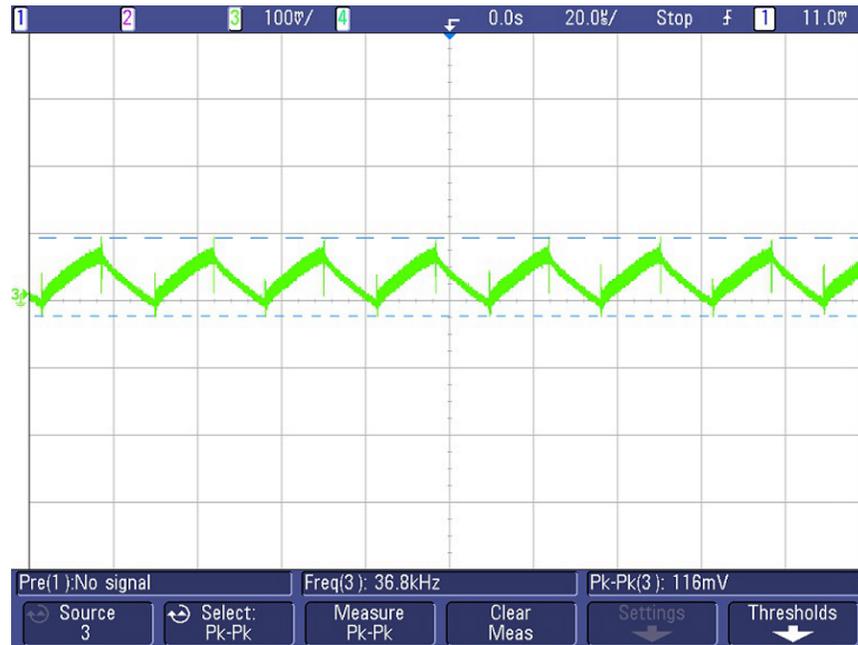


图 11. ISOW7841 DC Output Ripple

#### 4.2.4 ISOW7841 Input Switching Current

图 12 显示了为 DC 输入电流 160 mA 测量的输入开关电流。施加的输入电压为 3.3-V DC。

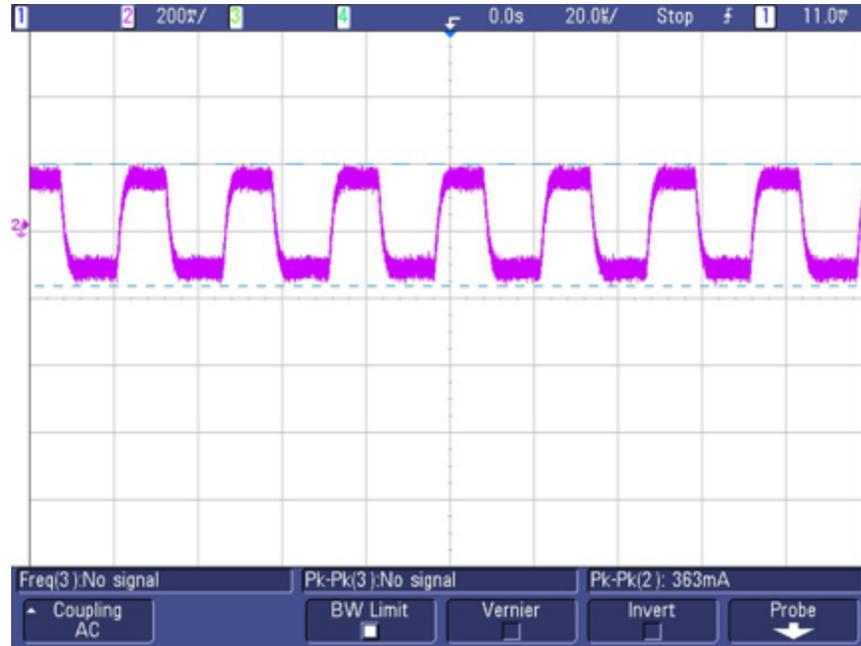


图 12. Input Switching Current for 75-mA Output Loading

#### 4.2.5 ISOW7841 Hotspot Monitoring

ISOW7841 的输出加载为 80 mA，热点在 30 分钟后进行了监测。图 13 显示了 ISOW784x 评估模块上的热点测量。

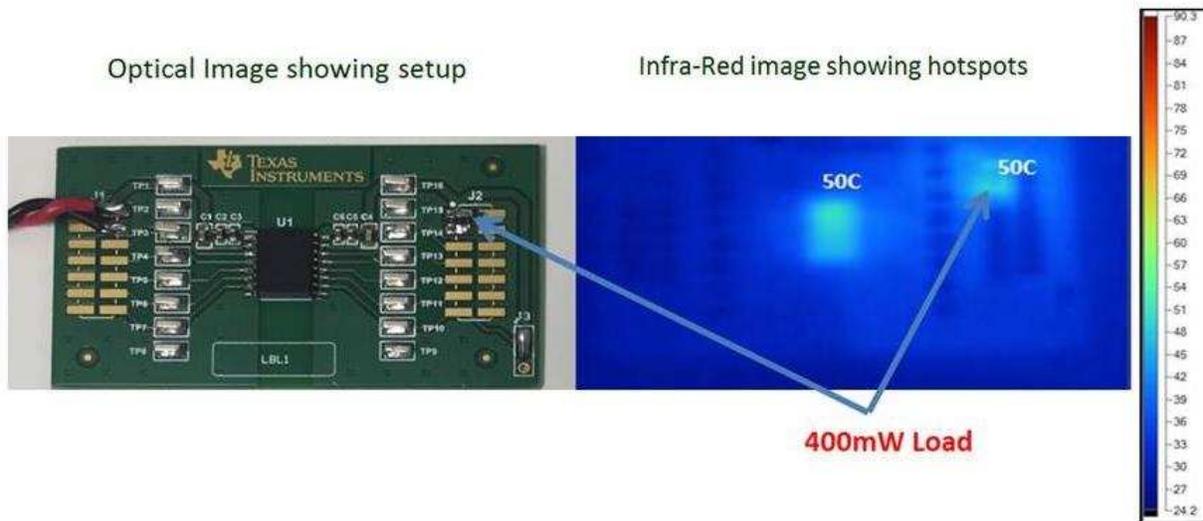


图 13. ISOW7841 Hotspot Capture With 80-mA Load

### 4.3 Performance Testing

This section provides information on the performance tests that are performed on the BIM.

#### 4.3.1 Voltage Measurement Accuracy

注: The reading in 表 20 is the measurements taken without any calibration. The accuracy can be improved by introducing software calibration. The errors observed can be further improved by doing a gain calibration. To ensure that the results are less than  $\pm 3.0\%$  of measured value  $\pm 1$  V (programmable step size), applying gain calibration is recommended. The gain calibration can be applied on the host side or BIM side.

##### 4.3.1.1 Error in % of Measured Value for AC/DC BIM

表 20 summarizes the accuracy performance for different configuration of BIMs with different gains for AC or DC inputs.

表 20. Measurement Accuracy for AC/DC BIM

VOLTAGE INPUT (V)	INPUT TYPE	GAIN	A0 AND A3	A4 AND A1
15 to 48	AC, 50 Hz	High gain $\times 3.4$	Within $\pm 1.5\% \pm 1$ V	Within $\pm 1.5\% \pm 1$ V
48 to 276		Low gain $\times 1$	Within $\pm 1.5\% \pm 1$ V	Within $\pm 1.5\% \pm 1$ V
15 to 48	DC	High gain $\times 3.4$	Within $\pm 1.5\% \pm 1$ V	Within $\pm 1.5\% \pm 1$ V
48 to 320		Low gain $\times 1$	Within $\pm 1.5\% \pm 1$ V	Within $\pm 1.5\% \pm 1$ V

图 14 provides the DC measurement for the four ADC inputs configured to measure DC inputs with two gains.

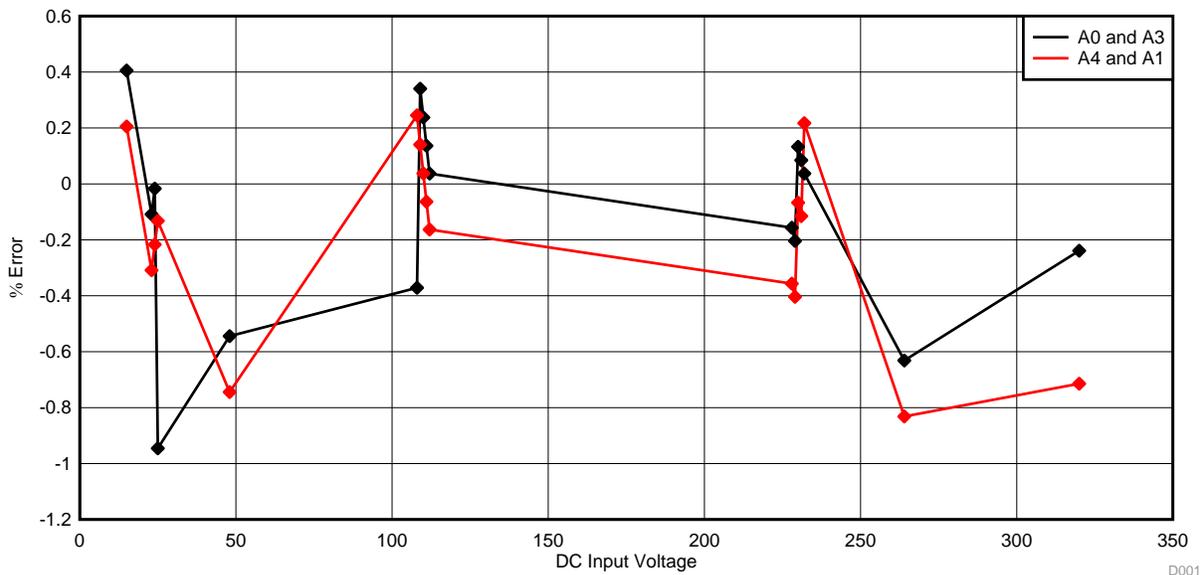


图 14. DC Input Voltage versus % Error of Measured Value Plot

### 4.3.1.2 Error in % of Measured Value for DC BIM

表 21 summarizes the accuracy performance for BIM with different combinations for digital isolators and MCUs.

表 21. Measurement Accuracy for DC BIM

MODULE TYPE	MEASUREMENT ACCURACY FOR INPUT CHANNELS			
	CH1	CH2	CH3	CH4
DC BIM with MSP430G2332 and ISOW7841	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V
DC BIM with MSP430G2332 and ISO7741	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V
DC BIM with MSP430FR2111 and ISOW7841	Within $\pm 1.5\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V	Within $\pm 1.2\% \pm 1$ V

### 4.3.2 Wetting Current Measurement

The wetting current required for binary inputs are generated using a fixed resistor and PWM control. The short time overload withstand capability of the resistors are used during generation of wetting current. 表 22 provides the current measured with duty cycle changed.

表 22. Wetting Current Measurement at Different Voltage Inputs (DC Only)

DC VOLTAGE (V SWITCHED FOR 50 ms)	IMPEDANCE (k $\Omega$ )	INPUT 1 CURRENT (mA)	DUTY CYCLE	INPUT 2 CURRENT (mA)	DUTY CYCLE
24	2.5	$\approx 9$	N/A	$\approx 9$	N/A
110		$\approx 44$	N/A	$\approx 44$	N/A
230		$\approx 44$	50%	$\approx 44$	50%

### 4.3.3 Digital Isolator Functional Testing Using SPI

After the MSP430G2332 starts up, there is a 3- to 5-second initial delay before the MCU starts accepting packets from the MSP430FR5969. During this delay, the LED should be turned off for this entire duration. Also, the watchdog is disabled during this time interval. Once the initial delay has passed, the watchdog and communication to the MSP430FR5969 is enabled. The watchdog is cleared whenever a packet is received from the MSP430FR5969. If the time interval between successive packets received by the MSP430G2332 is greater than 660 ms, then the watchdog would restart the MSP430G2332.

For the communication, the MSP430FR5969 sends a one-character packet to the MSP430G2332 once every 50 ms using a 500-kbps SPI clock. The value of the actual character sent is equal to the value of the previous character sent incremented by 1. Every time the MSP430FR5969 sends a packet to the MSP430G2332, the state of the green LED2 on the MSP430FR5969 LaunchPad™ is toggled.

Once the MSP430G2332 receives a packet, it toggles the P2.4 pin, connected to an LED on the board. The MSP430G2332 would then echo the packet received from the MSP430FR5969 back to the MSP430FR5969. Whenever a packet is received from the MSP430G2332, the MSP430FR5969 verifies if the packet has the expected value. If the packet has the expected devalue, LED1 on the LaunchPad would toggle its state.

To connect the proper SPI pins from the MSP430FR5969 LaunchPad to the MSP430G2332, the FET emulation jumpers had to be removed. As a result, for programming the MSP430FR5969, the TI FET tool was used instead of the direct USB connection option. The following pins on the MSP430FR5969 LaunchPad were used for connecting to MSP430G2332 P1.5 of MSP430FR5969 LaunchPad to P1.5 (SCLK, pin 7) of MSP430G2332. TXD on the emulation header of the MSP430FR5969 LaunchPad to P1.7 (SDI, pin 15) of the MSP430G2332. RXD of the emulation header of the MSP430FR5969 LaunchPad to P1.6 (SDO, pin 14) of the MSP430G2332.

#### 4.3.3.1 MSP430FR5969 LaunchPad

The MSP-EXP430FR5969 LaunchPad Development Kit is an easy-to-use MCU development board for the MSP430FR5969 MCU. It contains everything needed to start developing quickly on the MSP430FRxx FRAM platform, including onboard emulation for programming, debugging, and energy measurements. The board features onboard buttons and LEDs for integration of a simple user interface. The MSP430FR5969 MCU features embedded FRAM, a non-volatile memory known for its ultra-low-power, high endurance, and high-speed write capabilities (see the [MSP-EXP430FR5969](#) product page).

## 4.4 EMC Pre-Compliance Testing

The following EMC tests listed in [表 23](#) were performed.

**表 23. EMC Tests**

TESTS	PORTS	STANDARDS
ESD	Binary input terminals	IEC61000-4-2
Surge	Binary input terminals	IEC61000-4-5
EFT	Binary input terminals	IEC61000-4-4
Immunity to radio frequency induced signals	Binary input terminals	IEC 61000-4-6
Ring wave immunity	Binary input terminals	IEC 61000-4-12
Damped oscillatory waves immunity	Binary input terminals	IEC 61000-4-18

[表 24](#) provides information on the different criteria use to indicate the performance of the device under test.

**表 24. Performance Criteria**

CRITERIA	PERFORMANCE (PASS) CRITERIA
A	The module must continue to operate as intended. No loss of function or performance even during the test.
B	Temporary degradation of performance is accepted. After the test, the module must continue to operate as intended without manual intervention.
C	During the test, loss of functions accepted, but no destruction of hardware or software. After the test, the module must continue to operate as intended automatically, after manual restart, or power off/power on.

#### 4.4.1 Note on Performance Testing

The following voltages were applied to the BIM for testing:

- Power supply for BIM operation: 3.3 to 3.6 V
- Binary input for measurement: 30-V DC

**Performance testing procedure:** To test the BIM performance, a 10-kHz clock was generated by the MCU, the output was connected to the ISOW7841/ISO7741 input, and the output of the isolator was looped back to three inputs or the ISOW7841 or ISO interfaced to the MCU. The MCU blinks an LED if it receives back the pulse. On power up, the module clock is off and the clock is generated by applying a sequence of input to the ISOW7841 digital input.

#### 4.4.2 Power Supply Connection

Depending on the test performed, the power was connected to the host side of the ISOW7841 as shown in 表 25.

表 25. Power Supply Connection

TESTS	TEST PORT	POWER SOURCE	COMMENTS
IEC61000-4-2	Binary inputs	Battery source regulated to 3.6 V	Test 1: ESD power earth was referenced to GND1
IEC61000-4-4, IEC61000-4-5	Binary inputs	DC voltage source (table top) 3.45 V	EFT and surge generator power earth was referenced to GND1
IEC61000-4-6,	Binary inputs	Battery source regulated to 3.6 V	Test equipment influences DC power supply (source) performance
IEC61000-4-12, IEC61000-4-18	Binary inputs	Battery source regulated to 3.6 V	Ring wave generator power earth was referenced to GND1
EN55022 CE and RE	Binary inputs	Battery source regulated to 3.6 V	Looking for emission from the BIM only

#### 4.4.3 IEC61000-4-2 ESD Test

The IEC61000-4-2 electrostatic discharge (ESD) test simulates the electrostatic discharge of an operator directly onto an adjacent electronic component. An electrostatic charge usually develops in low relative humidity and on low-conductivity carpets or vinyl garments. The capacity of the body can be charged to several kilovolts and is discharged when contact is made with an electronic unit or system. The discharges are harmless to humans, but not too sensitive, electronic equipment. The resulting currents cause interference or even component damage.

The test conditions are as follows:

- Five positive and five negative pulses
- Contact discharge

表 26. ESD Test Observations for ISOW7841

TEST STANDARD	TEST VOLTAGE (kV)	OBSERVATION 2-CHANNEL AC/DC	OBSERVATION 4-CHANNEL DC	OBSERVATION 4-CHANNEL DC_FRAM
IEC61000-4-2	2	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-2	4	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-2	6	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-2	8	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-2	9	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A

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注: The same was tested with the ISO7741 for all of these conditions. The performance test as per 节 4.4.1 was done before, during, and after the tests and there was no change in performance.

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#### 4.4.4 IEC61000-4-4 EFT Test

Industrial measurement and control equipment nearly always use conventional control units containing relays or other electro-mechanical switching devices. Fluorescent lamp ballast units and insufficiently suppressed motors (hair dryers, vacuum cleaners, drills, and so on) are found everywhere in the public power supply.

The test conditions are as follows:

- EFT, DM
- 5 and 100 kHz
- 1 minute
- Positive and negative

**表 27. EFT Test Observations for ISOW7841**

TEST STANDARD	TEST VOLTAGE (kV)	OBSERVATION 2-CHANNEL AC/DC	OBSERVATION 4-CHANNEL DC	OBSERVATION 4-CHANNEL DC_FRAM
IEC61000-4-4	1.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-4	2.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-4	2.5	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A

注: The same was tested with the ISO7741 for all of these conditions. The performance test as per 节 4.4.1 was done before, during, and after the tests and there was no change in performance.

#### 4.4.5 IEC61000-4-5 Surge Test

Surge events are generated by lightning phenomena, switching transients, or protection devices in the power distribution system. A surge is influenced by the propagation path resulting in different forms depending upon where a measurement is taken. Combination wave generators (CWG) simulate a surge event in power lines close to or within buildings.

The test conditions are as follows:

- DM
- positive and negative polarity
- 5 pulses

表 28. Surge Test Observations for ISOW7841

TEST STANDARD	TEST VOLTAGE (kV)	OBSERVATION 2-CHANNEL AC/DC	OBSERVATION 4-CHANNEL DC	OBSERVATION 4-CHANNEL DC_FRAM
IEC61000-4-5	1.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-5	2.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-5	2.5	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A

注: The same was tested with the ISO7741 for all of these conditions. The performance test as per 节 4.4.1 was done before, during, and after the tests and there was no change in performance.

#### 4.4.6 IEC61000-4-6 Conducted Susceptibility

This test is defined as a product's relative ability to withstand electromagnetic energy that penetrates it through external cables, power cords, input/output (I/O) interconnects, or chassis. In order to verify immunity, electromagnetic energy in the frequency range of 150 kHz to 80 MHz is induced into the product through each cable and interconnect and the product is expected to operate within the set criteria. The upper limit of the frequency range can go up to 100 MHz depending on the applicable standard.

The test conditions are as follows:

- 10-V EMF at 1-kHz 80% am
- 150 kHz to 80 MHz
- Dwell time of 0.5 seconds every 1 seconds

表 29. Conducted Susceptibility Test Observations for ISOW7841

TEST STANDARD	DWELL TIME (SEC)	OBSERVATION 2-CHANNEL AC/DC BIM	OBSERVATION 4-CHANNEL DC BIM
IEC61000-4-6	0.5	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-6	1.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A

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注: The same was tested with the ISO7741 for all of these conditions. The performance test as per 节 4.4.1 was done before, during, and after the tests and there was no change in performance.

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#### 4.4.7 IEC61000-4-12 and IEC61000-4-18 Ring Wave and Damped Sine Wave

The ring wave (non-repetitive) appears at the terminals of equipment as a consequence of switching in power and control lines, as well as a consequence of lightning. The ring wave test is applicable to equipment connected to AC mains. The damped oscillatory wave (repetitive) appears at the terminals of equipment as a consequence of switching with restriking of the arc. The damped oscillatory wave test is applicable to equipment used in high-voltage substations (static relays). But with a frequency of 1 MHz only, this test has existed for a long time under IEC 255-4, appendix E5: High frequency disturbance test, also known as ANSI/IEEE C.37.90a-1989, and has been transferred to IEC 60255-22-1: Electrical disturbance tests for measuring relays and protection equipment (1-MHz burst disturbance tests).

表 30 provides the observation for ring wave tests done at different test levels. The test conditions are as follows:

- DM 100 kHz
- 40 pulses per second positive and negative polarity
- Pulses applied for 2 seconds every 10 seconds
- Test duration of 1 minute positive and negative polarity

表 30. Ring Wave Test Observations for ISOW7841

TEST STANDARD	TEST VOLTAGE (kV)	OBSERVATION 2-CHANNEL AC/DC	OBSERVATION 4-CHANNEL DC
IEC61000-4-12	0.5	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-12	1.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-12	2.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A

表 31 provides the observation for damped sine wave tests done at different test levels. The test conditions are as follows:

- DM 1 MHz  $\pm$  10% 1 MHz
- 400 pulses per second
- Positive and negative polarity
- Pulses applied for 2 seconds every 10 seconds

表 31. Damped Sine Wave Test Observations for ISOW7841

TEST STANDARD	TEST VOLTAGE (kV)	OBSERVATION 2-CHANNEL AC/DC	OBSERVATION 4-CHANNEL DC
IEC61000-4-18	0.5	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-18	1.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A
IEC61000-4-18	2.0	Passed. No power supply droops. Meets Criteria A	Passed. No power supply droops. Meets Criteria A

注: The same was tested with the ISO7741 for all of these conditions. The performance test as per 节 4.4.1 was done before, during, and after the tests and there was no change in performance.

### 4.5 EMI Pre-Compliance Testing as per CISPR 22

Conducted emission measures any signals generated by equipment that appear on its power supply port and which can, therefore, be conducted into the power supply, and potentially disturb other ship's equipment. Radiated emission measures any signals radiated by equipment that can potentially disturb other equipment. For radiated emission testing, a common-mode filter was connected at the 3.3-V DC input of the ISOW7841 BIM. The power supply was connected using wires, and hence a common-mode filter was used. 图 15 provides the conducted emission plots for average and quasi-peak emission as per CISPR 22.

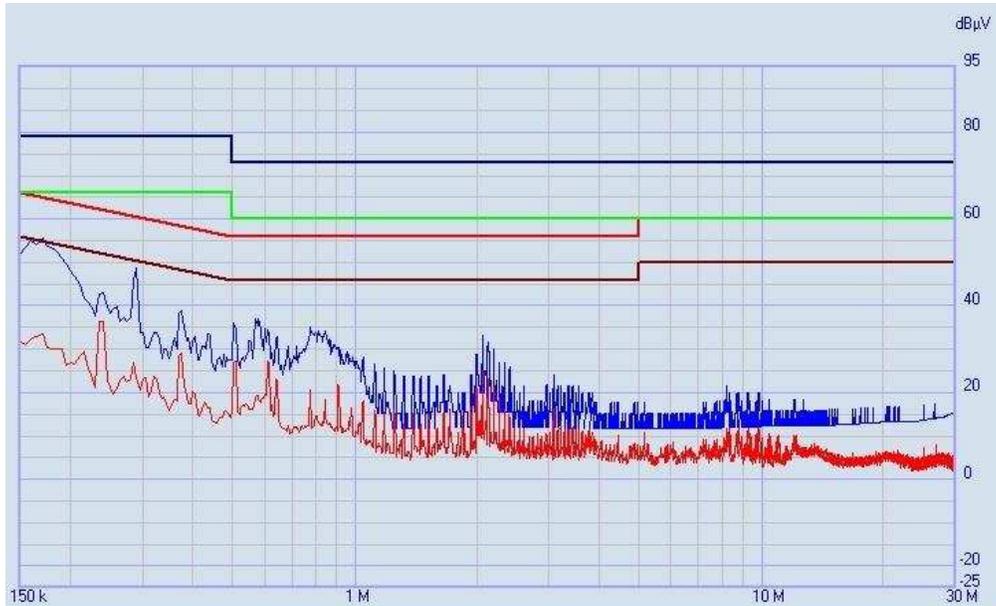


图 15. Conducted Emission Plot for ISOW7841-Based BIM

图 16 provides the radiated emission plots for quasi-peak emission as per CISPR 22.



图 16. Radiated Emission Plot for ISOW7841-Based BIM at 3 m

表 32 总结了导出的和辐射发射测试观察到的不同配置的二进制隔离器和数字隔离器。

**表 32. Conducted Emission Test and Radiated Emission Observations for ISOW7841**

TEST CONDITION	STANDARD	LIMIT	OBSERVATION 2-CHANNEL AC/DC	OBSERVATION 4-CHANNEL DC	OBSERVATION 4-CHANNEL DC_FRAM	OBSERVATION 4-CHANNEL DC WITH ISO7741
0.15 to 0.50 MHz, Class A	CISPR 22, CE	< 79 dB( $\mu$ V) quasi peak	Meets Class B emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)
0.5 to 30 MHz, Class A	CISPR 22, CE	< 73 dB( $\mu$ V) quasi peak	Meets Class B emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)
30 to 230 MHz, Class A measured at 3 meters	CISPR 22, RE	< 50 dB( $\mu$ V/m) quasi peak	Meets Class A emission requirements by > 10 dB( $\mu$ V)	Meets Class A emission requirements by > 10 dB( $\mu$ V)	Meets Class A emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)
230 to 1000 MHz, Class A measured at 3 meters	CISPR 22, RE	< 57 dB( $\mu$ V/m) quasi peak	Meets Class A emission requirements by > 10 dB( $\mu$ V)	Meets Class A emission requirements by > 10 dB( $\mu$ V)	Meets Class A emission requirements by > 10 dB( $\mu$ V)	Meets Class B emission requirements by > 10 dB( $\mu$ V)

注：辐射发射测试使用水平和垂直天线极化。在测试前、测试中以及测试后均进行了性能测试，如第 4.4.1 节所述，且未观察到性能变化。

## 4.6 Test Results Summary for BIMs

表 33 总结了在 BIM 上进行的测试和观察到的结果。BIM 准确地测量 DC 电压或 AC 电压输入，并且也满足 EMC 测试的预符合标准，如 IEC60000-4 系列和 CISPR 22 Class A。

**表 33. Test Results Summary**

TEST	OBSERVATION
Power supply: ISOW7841 output	OK
Transformer drive-based power supply output	OK
MCU programming: MSP430G2332 or MSP430FR2111	OK
Wetting current for AC/DC type binary input module	OK
Gain and reference stage performance	OK
AC/DC input voltage measurement accuracy	OK
DC voltage measurement accuracy	OK
Digital isolator functional performance	OK
IEC6-1000-4-2	Pass
IEC6-1000-4-4	Pass
IEC6-1000-4-5	Pass
IEC6-1000-4-6	Pass
IEC6-1000-4-12	Pass
IEC6-1000-4-18	Pass
EN55022 CE Class A and Class B	Pass
EN55022 RE Class A	Pass

## 5 Design Files

### 5.1 Schematics

To download the schematics, see the design files at [TIDA-00847](#).

### 5.2 Bill of Materials

To download the bill of materials (BOM), see the design files at [TIDA-00847](#).

### 5.3 PCB Layout Recommendations

#### 5.3.1 Layout Prints

To download the layer plots, see the design files at [TIDA-00847](#).

### 5.4 Altium Project

To download the Altium project files, see the design files at [TIDA-00847](#).

### 5.5 Gerber Files

To download the Gerber files, see the design files at [TIDA-00847](#).

### 5.6 Assembly Drawings

To download the assembly drawings, see the design files at [TIDA-00847](#).

## 6 Related Documentation

1. Texas Instruments, [EMC Compliant, Isolated, 2-Channel Binary or Digital Input Module for Wide AC/DC Input Reference Design](#), TIDA-00809 Design Guide (TIDUBY6)
2. Texas Instruments, [EMC-Compliant Digitally Isolated 2-Channel, Wide DC Binary Input Module](#), TIDA-00420 Design Guide (TIDU858)

### 6.1 商标

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## 7 Terminology

**BIM**— Binary input module

**MCU**— Microcontroller unit

**AC** — Alternating current

**DC** — Direct current

**CE**— Conducted emission

**RE**— Radiated emission

## 8 About the Authors

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## 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

<b>Changes from Original (March 2017) to A Revision</b>	<b>Page</b>
• 已删除 从 <a href="#">资源</a> .....	1
• 已添加 在 <a href="#">资源</a> .....	1
• 已更改 MCU name from MSP430G2111 to MSP430FR2111 throughout design .....	7
• 已更改 MCU name from MSP430FR2332 to MSP430G2332 throughout design guide .....	8
• 已添加 CE to <a href="#">7 节</a> .....	45
• 已添加 RE to <a href="#">7 节</a> .....	45

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